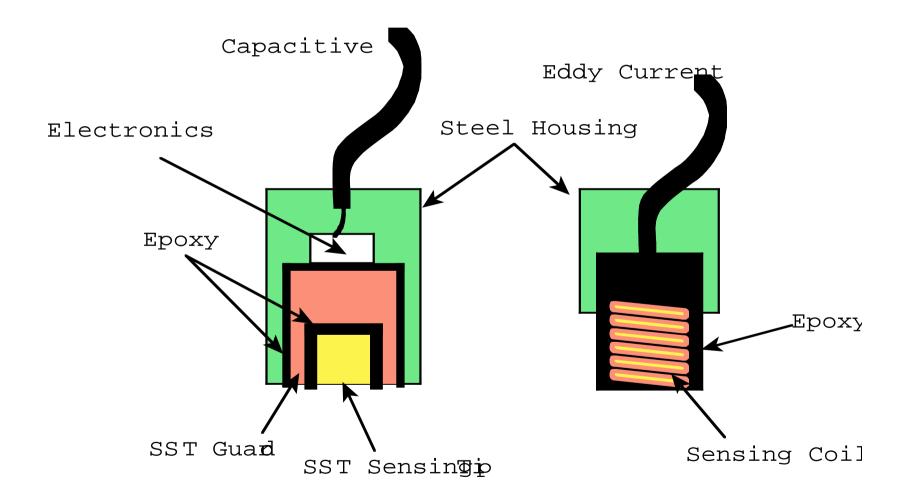
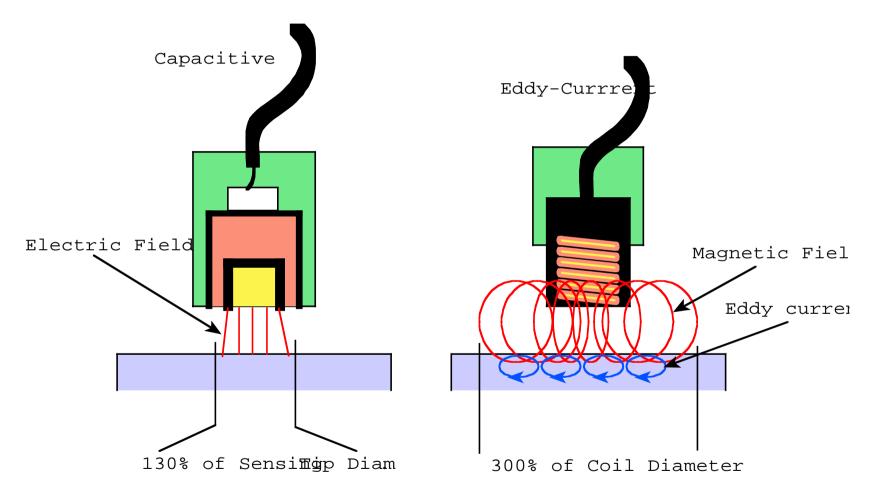
Choosing Between Capacitiv and Eddy-Current Sensors

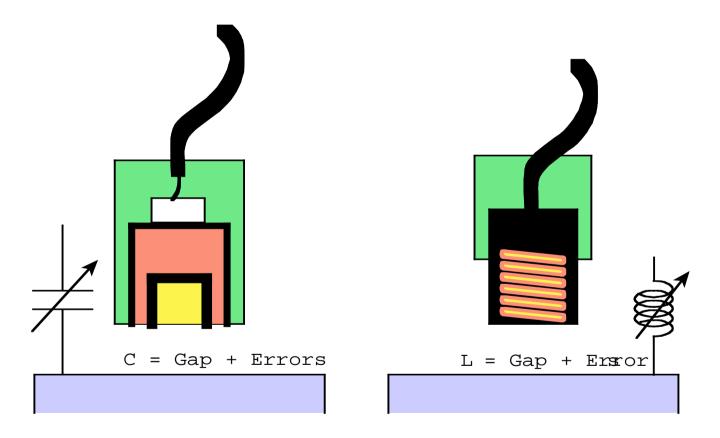
Construction

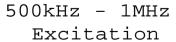


Fields and Target Size



Transduction Technique



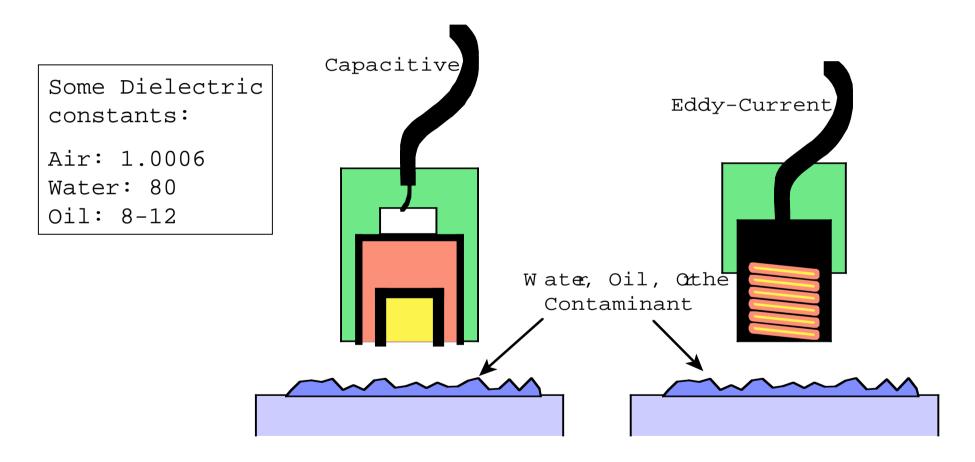


500kHz - 2.5MHz Excitation

Selecting Capacitive vs. E

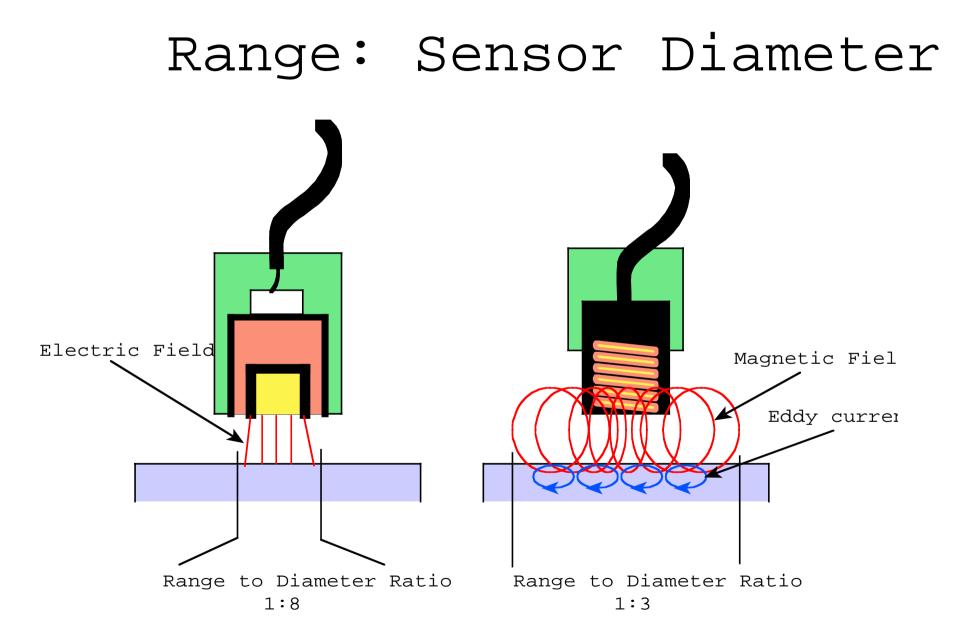
¥ Select to minimize error sources ¥ Following slides list error source di

Gap Contamination

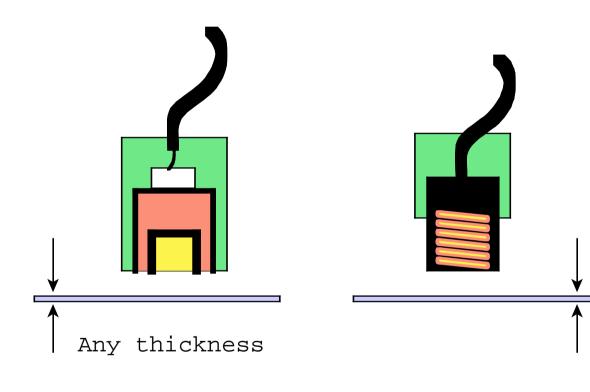


Output is affected by dielectric change.

Output is NOT affected by contamination.



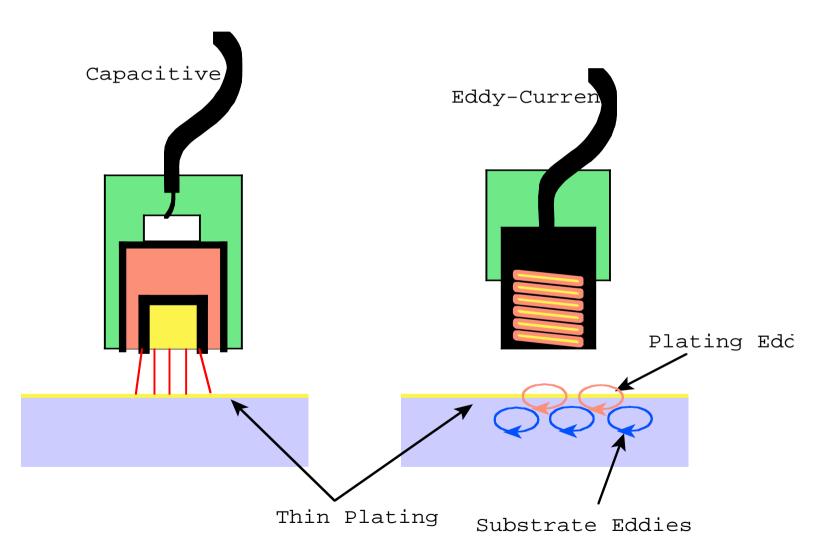
Minimum Target Thickness

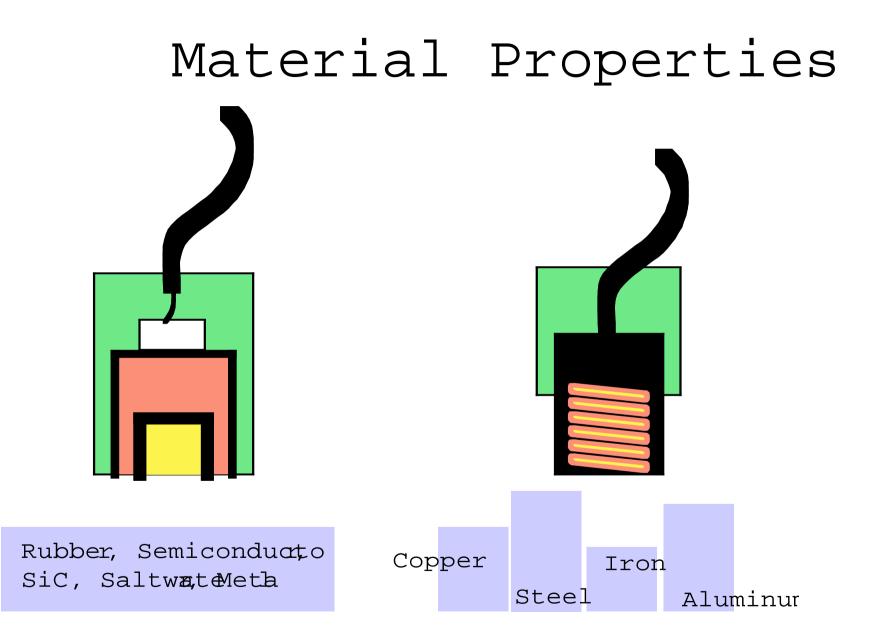


Eddy-Current Minimum thicknesses

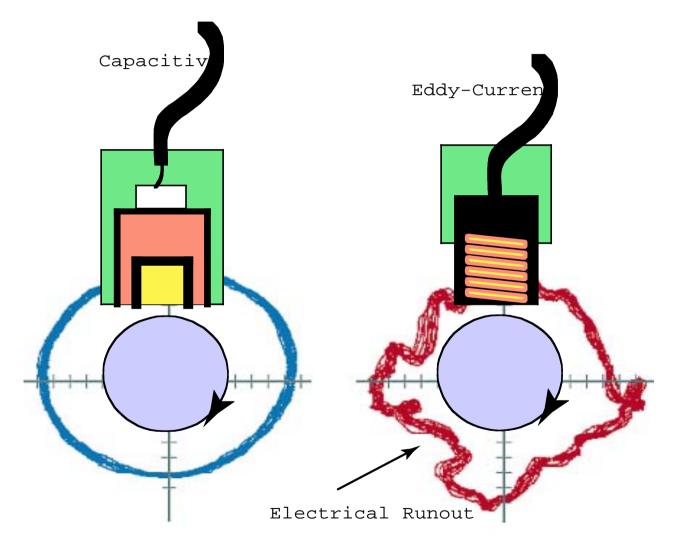
Silver: 0.19mm Copper: 0.20mm Gold: 0.22mm Aluminum: 0.24mm Zinc: 0.37mm 304 SST: 0.40mm Lead: 0.69mm Brass: 1.59mm Nickel: 0.04mm 1040 Steel: 0.01mm 416 Stainless: 0.08mm Iron: 0.59mm

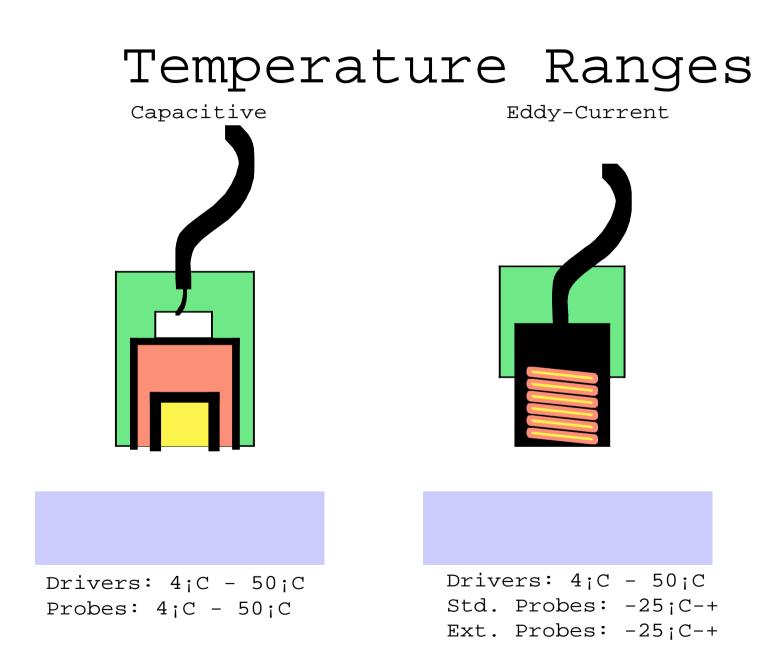
Plated Targets



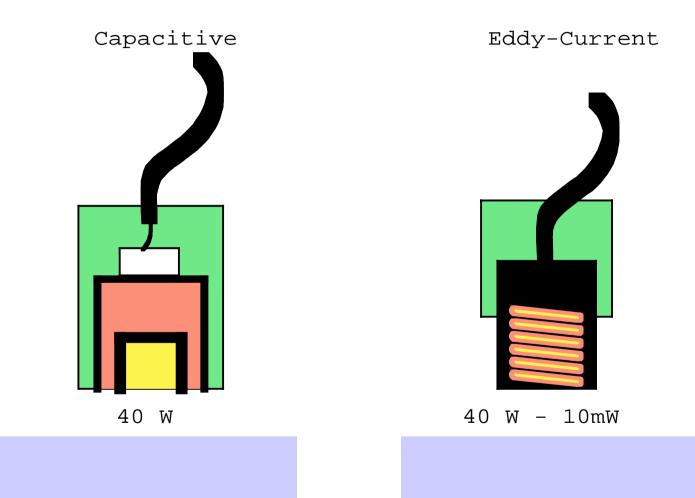


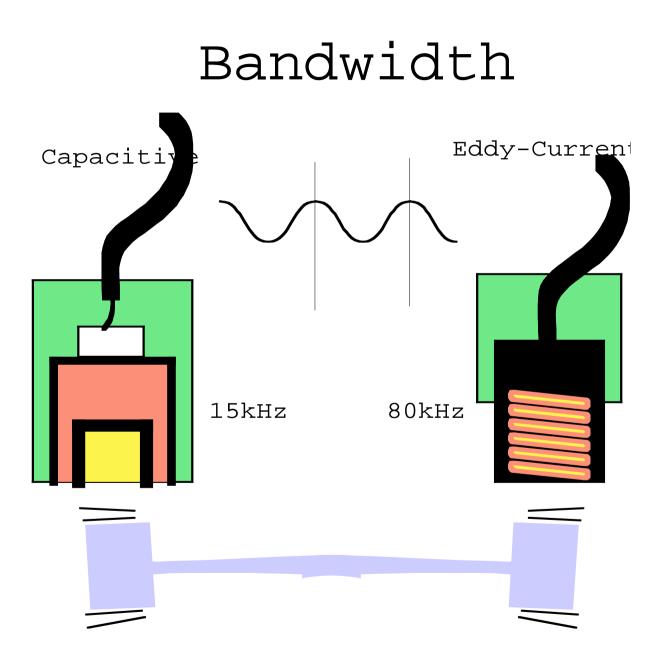
Rotating Targets



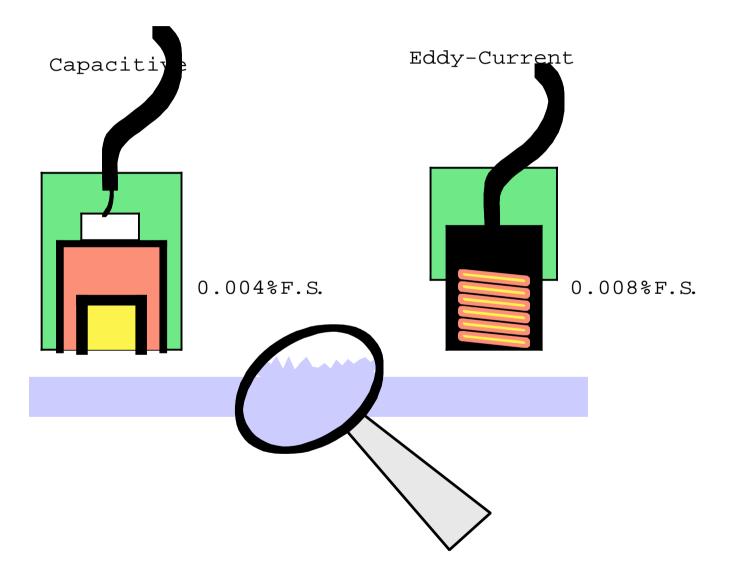


Vacuum Compatibility

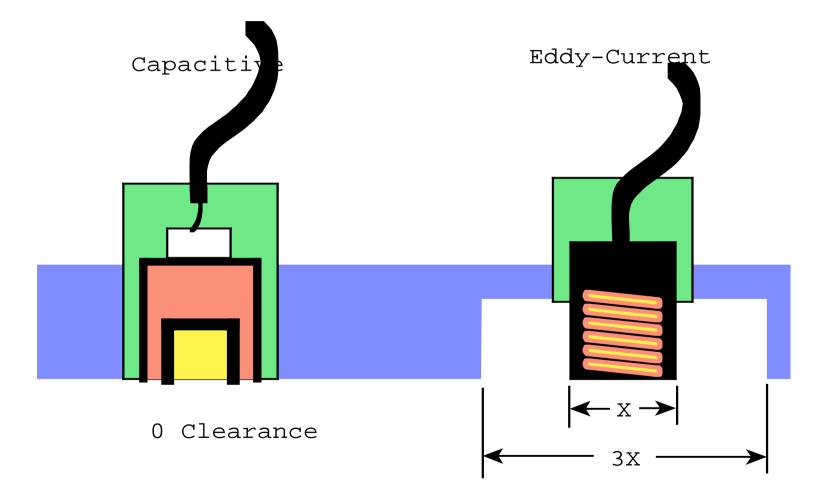




Resolution



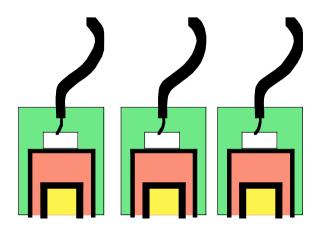
Flush Mounting Clearances

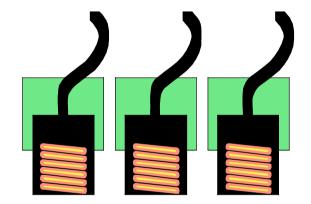


Multiple Proximate Probes

Capacitive

Eddy-Current

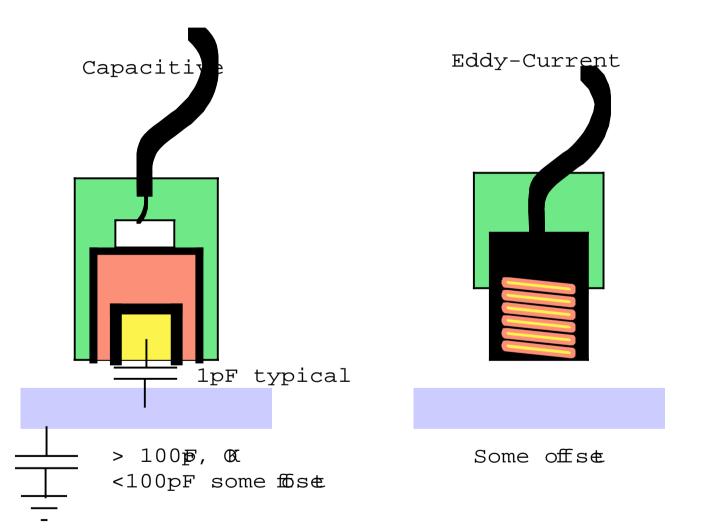




Special calibratior

OK

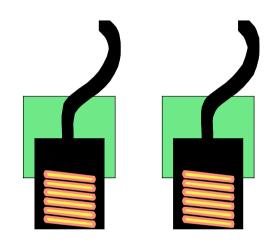
Ungrounded Targets



Ungrounded Solution (Cap)

Capacitive

180; Phase, No grounding necessary Eddy-Current



180; Phase, no advantage

Comparison

	Сар	Eddy		Сар	Eddy
Gap Contamination	_	+++	Bandwidth	++	+++
Small Target	+++	+	Resolution	+++	++
Large range/small pr	obe +	+++	Flush mounting	+++	+
Thin targets	+++	+	Proximate probes	+++	+
Plated targets	+++	+	Ungrounded Target	++	++
Changing material properties	+++	+	Vacuum	+++	++
Wide temp. range	+	+++	Budget	++	+++

New Eddy-Current Technology

¥Digital Signal Processing Core

- -Near perfect linearity
- -Near zero probe temperature drift
- -Development nearly complete

Conclusion

¥ Technology choice based on applicatio

- -Minimize error sources
- -Maximize strengths
- ¥Use the comparison checklist